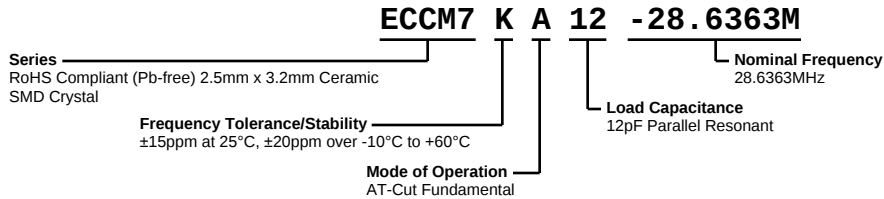


ECCM7KA12-28.6363M



ELECTRICAL SPECIFICATIONS

Nominal Frequency	28.6363MHz
Frequency Tolerance/Stability	$\pm 15\text{ppm}$ at 25°C, $\pm 20\text{ppm}$ over -10°C to +60°C
Aging at 25°C	$\pm 3\text{ppm}/\text{Year}$ Maximum
Load Capacitance	12pF Parallel Resonant
Shunt Capacitance (C0)	5pF Maximum
Equivalent Series Resistance	80 Ohms Maximum
Mode of Operation	AT-Cut Fundamental
Drive Level	100μWatts Maximum
Crystal Cut	AT-Cut
Spurious Response	>3dB (from Fo to Fo +5000ppm)
Storage Temperature Range	-40°C to +85°C
Insulation Resistance	500 Megaohms Minimum at 100Vdc

ENVIRONMENTAL & MECHANICAL SPECIFICATIONS

ESD Susceptibility	MIL-STD-883, Method 3015, Class 1, HBM: 1500V
Fine Leak Test	MIL-STD-883, Method 1014, Condition A
Flammability	UL94-V0
Gross Leak Test	MIL-STD-883, Method 1014, Condition C
Mechanical Shock	MIL-STD-883, Method 2002, Condition B
Moisture Resistance	MIL-STD-883, Method 1004
Moisture Sensitivity	J-STD-020, MSL 1
Resistance to Soldering Heat	MIL-STD-202, Method 210, Condition K
Resistance to Solvents	MIL-STD-202, Method 215
Solderability	MIL-STD-883, Method 2003
Temperature Cycling	MIL-STD-883, Method 1010, Condition B
Vibration	MIL-STD-883, Method 2007, Condition A

MECHANICAL DIMENSIONS (all dimensions in millimeters)



PIN	CONNECTION
1	Crystal
2	Cover/Ground
3	Crystal
4	Cover/Ground

LINE	MARKING
1	E28.6 E=Ecliptek Designator
2	XXXXX XXXXX=Ecliptek Manufacturing Identifier

ECCM7KA12-28.6363M

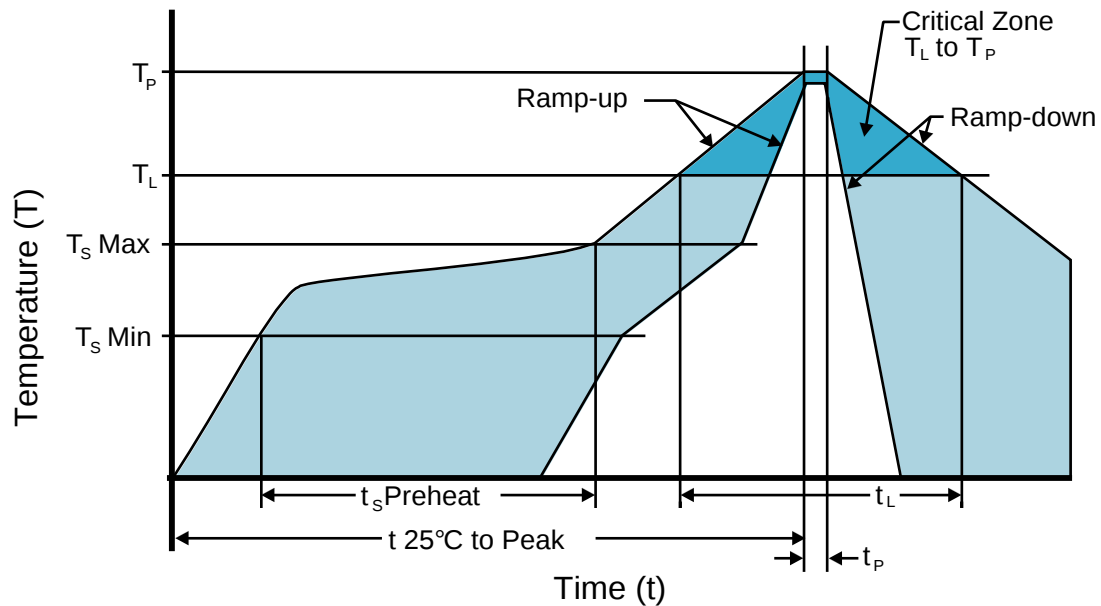
Suggested Solder Pad Layout

All Dimensions in Millimeters



All Tolerances are ± 0.1

Recommended Solder Reflow Methods



High Temperature Infrared/Convection

$T_S \text{ MAX to } T_L$ (Ramp-up Rate)	3°C/second Maximum
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Preheat

- Temperature Minimum ($T_S \text{ MIN}$)	150°C
- Temperature Typical ($T_S \text{ TYP}$)	175°C
- Temperature Maximum ($T_S \text{ MAX}$)	200°C
- Time ($t_s \text{ MIN}$)	60 - 180 Seconds

Ramp-up Rate (T_L to T_P)	3°C/second Maximum
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Time Maintained Above:

- Temperature (T_L)	217°C
- Time (t_L)	60 - 150 Seconds

Peak Temperature (T_P)	260°C Maximum for 10 Seconds Maximum
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Target Peak Temperature ($T_P \text{ Target}$)	250°C +0/-5°C
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Time within 5°C of actual peak (t_p)	20 - 40 seconds
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Ramp-down Rate	6°C/second Maximum
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Time 25°C to Peak Temperature (t)	8 minutes Maximum
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Moisture Sensitivity Level	Level 1
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Recommended Solder Reflow Methods



Low Temperature Infrared/Convection 245°C

T_S MAX to T_L (Ramp-up Rate) 5°C/second Maximum

Preheat

- Temperature Minimum (T_S MIN) N/A
 - Temperature Typical (T_S TYP) 150°C
 - Temperature Maximum (T_S MAX) N/A
 - Time (t_s MIN) 30 - 60 Seconds

Ramp-up Rate (T_L to T_P) 5°C/second Maximum

Time Maintained Above:

- Temperature (T_L) 150°C
 - Time (t_L) 200 Seconds Maximum

Peak Temperature (T_P) 245°C Maximum

Target Peak Temperature (T_P Target) 245°C Maximum 2 Times / 230°C Maximum 1 Time

Time within 5°C of actual peak (t_P) 10 seconds Maximum 2 Times / 80 seconds Maximum 1 Time

Ramp-down Rate 5°C/second Maximum

Time 25°C to Peak Temperature (t) N/A

Moisture Sensitivity Level Level 1

Low Temperature Manual Soldering

185°C Maximum for 10 seconds Maximum, 2 times Maximum.

High Temperature Manual Soldering

260°C Maximum for 5 seconds Maximum, 2 times Maximum.